

RKP201KK

Silicon Epitaxial Trench Pin Diode for Antenna Switching

REJ03G1224-0200 Rev.2.00 Sep 06, 2005

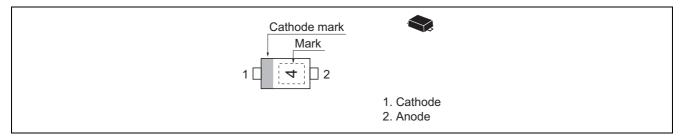
Features

- Adopting the trench structure minimize terminal capacitance. (C = 0.35 pF max)
- Low forward resistance. ($rf = 2.0 \Omega max$)
- Low operation current.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Name	Package Code (Previous Code)
RKP201KK	4	SFP	PUSF0002ZB-A
			(SFP)

Pin Arrangement





Absolute Maximum Ratings

			(Ta = 25°C)	
Item	Symbol	Ratings	Unit	
Reverse voltage	V _R	30	V	
Forward current	lF	100	mA	
Power dissipation	Pd	150	mW	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	۵°	

Electrical Characteristics

(Ta = 25°C)

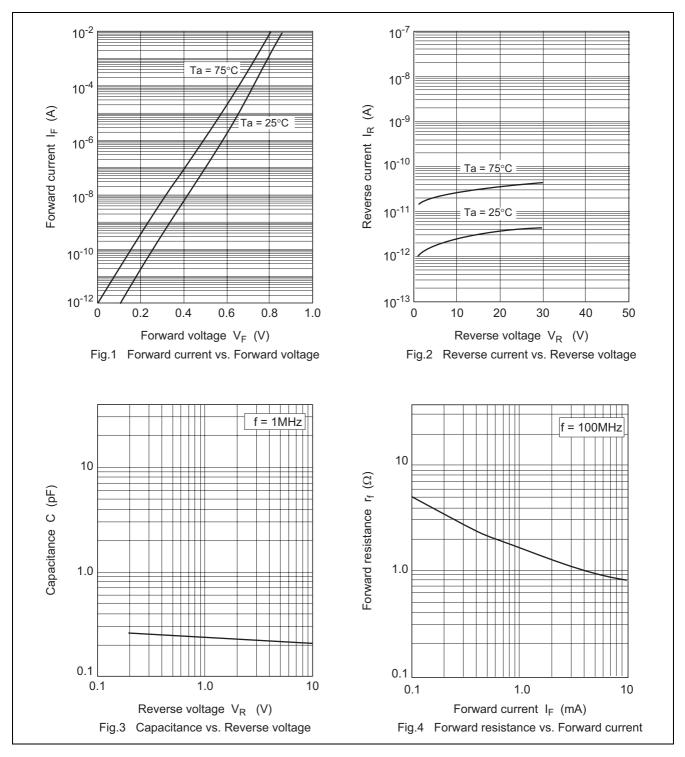
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _R	—	—	100	nA	V _R = 30 V
Forward voltage	V _F	—	—	0.9	V	$I_F = 2 \text{ mA}$
Capacitance	С	—	—	0.35	pF	$V_R = 1 V, f = 1 MHz$
Forward resistance	r _f	_	_	2.0	Ω	I _F = 2 mA, f = 100 MHz
ESD-Capability *1	—	100			V	C = 200 pF, R = 0 Ω , Both forward and reverse direction 1 pulse.

Notes: 1. Failure criterion ; $I_R > 100 \ nA$ at V_R = 30 V

2. SFP package, the material of lead is exposed for cutting plane. There for, soldering nature of lead tip part is considered as unquestioned. Please kindly consider soldering nature.

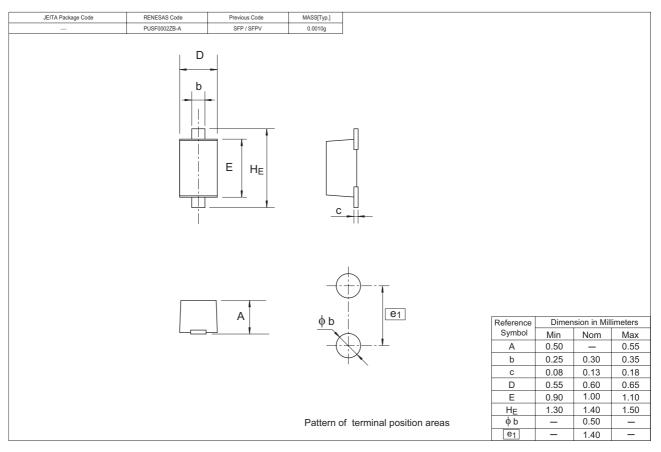


Main Characteristic





Package Dimensions





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